Product Change Notification

110746 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: **110746 - 00**

Change Title: **Selected Intel® ICH6 and ICH8 I/O Controller Hubs, PCN 110746-00, Product Material**

Date of Publication: **September 30, 2011**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 02, 2011

Description of Change to the Customer:

Intel's selected ICH6 and ICH8 product wire bond material is changing from Gold (Au) to Copper Palladium (Cu-Pd).

Specifics of the change are:

- With recent advancements made in copper bonding, most of the assembly suppliers are switching to Cu-Pd as mainstream bonding process. Intel is following the High Volume Manufacturing (HVM) trend.
- Cu-Pd products are one-to-one pin compatible with Au products and there is no form, fit, function change.
- See "Products Affected/Intel Ordering Codes" table below for new marketing name, s-spec and MM#s.
- The products with the new marking have identical quality and reliability as the current products.

Customer Impact of Change and Recommended Action:

- Intel is moving with the rest of the industry per JEDEC standards.
- There are no changes to form, fit or function.
- The Cu-Pd and Au parts are totally compatible with each other.
- Customers do not need to do anything different in the receipt and use of the Cu-Pd products in their manufacturing process.
- Customers could get gold wire or copper palladium wire products until inventory is depleted.

Products Affected / Intel Ordering Codes:

Intel® I/O Controller Hubs						
	Pre Conversion			Post Conversion		
Marketing Name	**Product Code**	**S-Spec**	**MM#**	**Product Code**	**S-Spec**	**MM#**
Intel® 82801HR	NH82801HR S L9MK	S L9MK	883292	DW82801HR S LJA9	S LJA9	917577
Intel® 82801HB	NH82801HB S L9MN	S L9MN	883306	DW82801HB S LJEW	S LJEW	917657
Intel® 82801HBM	NH82801HBM S LB9A	S LB9A	898274	DW82801HBM S LJ4Y	S LJ4Y	915071
Intel® 82801HEM	NH82801HEM S LB9B	S LB9B	898282	DW82801HEM S LJ4Z	S LJ4Z	915072
Intel® 82801FB	FW82801FB S L7Y5	S L7Y5	865377	EF82801FB S LJH3	S LJH3	918329
Intel® 82801FBM	NH82801FBM S L89K	S L89K	868158	DW82801FBM S LJGN	S LJGN	918234
Intel® 82801FB	NH82801FB S L89L	S L89L	868390	DW82801FB S LJGP	S LJGP	918235
Intel® 82801HO	NH82801HO S L9MM	S L9MM	883305	DW82801HO S LJAA	S LJAA	917578

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
September 30, 2011	00	Originally Published PCN